Product Specification

Number:	L-KLS1-WIFI-SMD3216
Name:	3.2 *1.6 *0.4 mm ³
	SMD Antenna
Customer:	
Date:	2025-08-06

Customer Signature:	



NINGBO KLS ELECTRONIC CO; LTD

Tel : 0086-574-86828566 Fax : 0086-574-86824882

ADD: NO. 8-1, RONGXIA RD. XIAPU SHANQIAN

INDUSTRIAL ZONE BEILUN NINGBO ZHEJIANG.

Compi	Check	Review	Approva
Jenny	Jack.C		



Part name	3.2 *1.6 *0.4 mm ³ SMD Antenna	Date	2025-08-06
Part number	L-KLS1-WIFI-SMD3216	Edition	V1
Department		Page	2/9

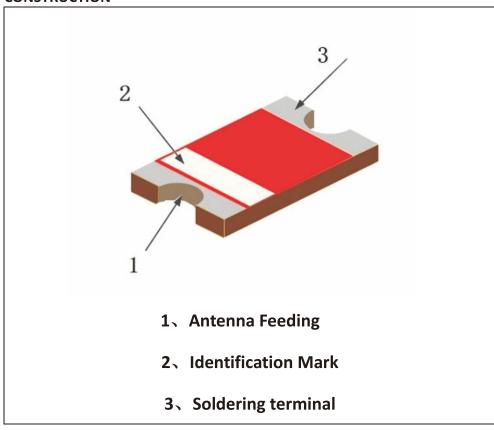
FEATURES

- 1. Surface Mounted Devices with a small dimension of 3.2 \times 1.6 \times 0.4 mm 3 meet miniaturization trend.
- 2. Low power loss and high antenna efficiency.
- 3. High stability in Temperature and Humidity Change.

APPLICATIONS

- 1. 2.4GHz ISM band RF applications
- 2. Bluetooth, Wireless, HomeRF

CONSTRUCTION



DIMENSIONS

Figure	Symbol	Dimension(mm)
a=0.6(mm) →	L	3.2 ±0.1
W= 1. 6 (mm)	w	1.6 ±0.1
L= 3. 2 (mm) T= 0. 4(mm)	Т	0.4 ±0.05
	а	0.6 ±0.1



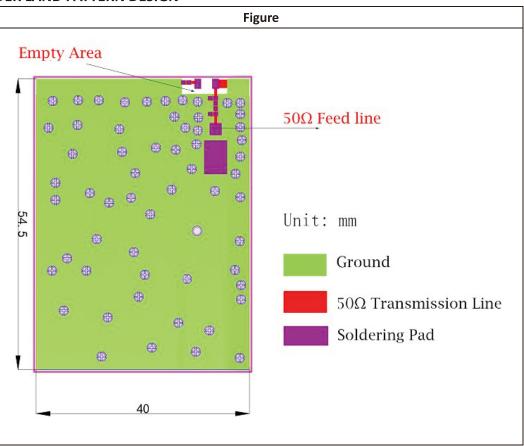
Part name	3.2 *1.6 *0.4 mm ³ SMD Antenna	Date	2025-08-06
Part number	L-KLS1-WIFI-SMD3216	Edition	V1
Department		Page	3 / 9

ELECTRICAL CHARACTERISTICS

WIFI-SMD3216	Specification	
Working Frequency Range	2450 ± 50MHz	
Band Width	>100MHz	
Impedance	50 Ω	
Gain(dBi)	0.2	
VSWR	<2	
Operation Temperature	-40℃~+85℃	
Power Capacity	3W	

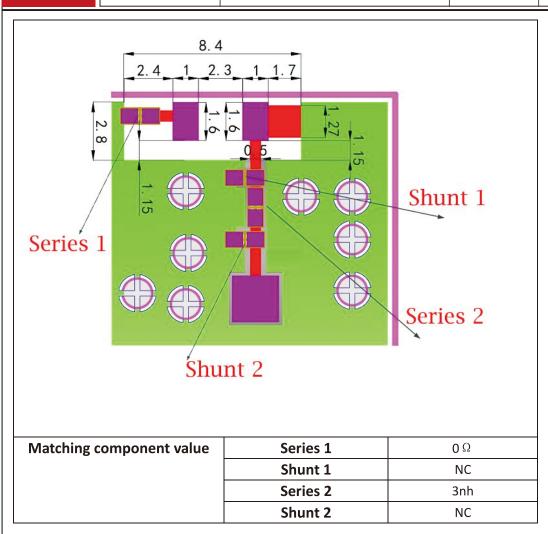
The working frequency need be adjusted to 2.45GHz with matching circuit.

SOLDER LAND PATTERN DESIGN

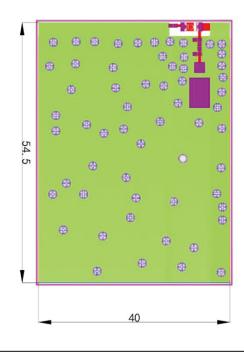




Part name	3.2 *1.6 *0.4 mm³ SMD Antenna	Date	2025-08-06
Part number	L-KLS1-WIFI-SMD3216	Edition	V1
Department		Page	4/9

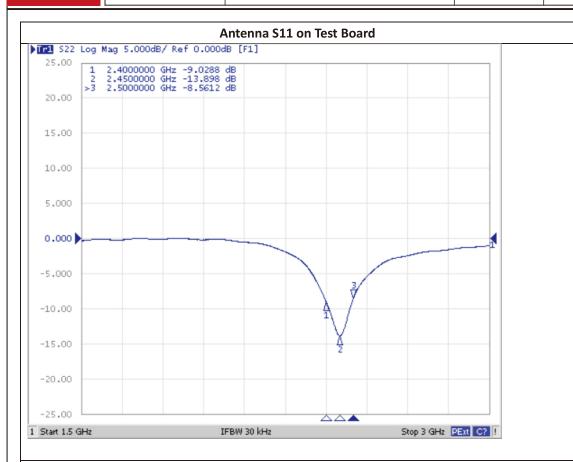


Antenna on Test Board (Thickness 1.0mm)





Part name	3.2 *1.6 *0.4 mm ³ SMD Antenna	Date	2025-08-06
Part number	L-KLS1-WIFI-SMD3216	Edition	V1
Department		Page	5/9



Antenna VSWR on Test Board

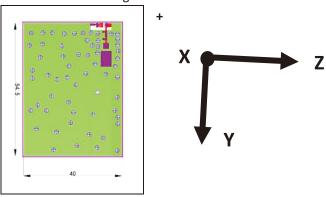


Efficiency and RADIATION PATTERN

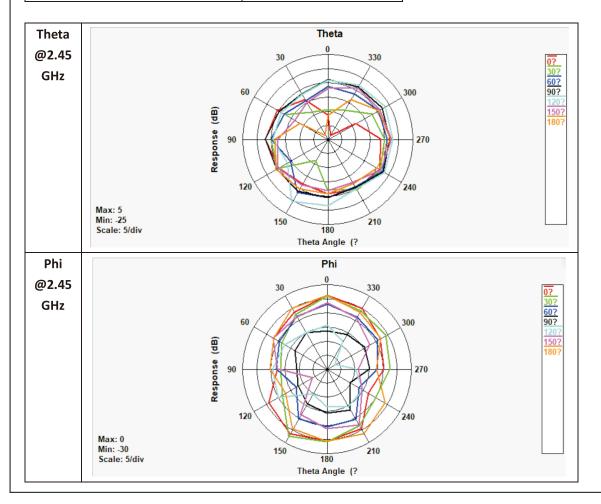


Part name	3.2 *1.6 *0.4 mm ³ SMD Antenna	Date	2025-08-06
Part number	L-KLS1-WIFI-SMD3216	Edition	V1
Department		Page	6 / 9

Efficiency, Radiation Pattern and Gain were dependent on measurement board design. The specification of CA-C01 antenna was measured based on the PCB size and installation position as shown in the below figure test board. The test results were tested in ETS 3D Chamber.

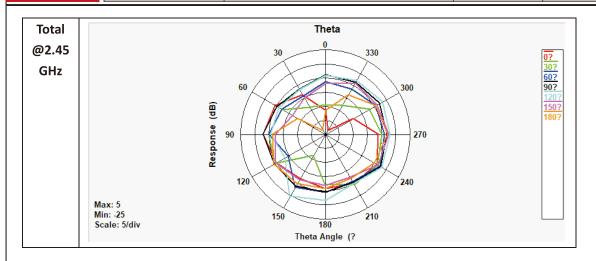


Gain and Efficiency	2.4G-2.5GHz	
Peak Gain	0.2dBi	
Average Gain across the band	0.06dBi	
Gain Range across the band	-0.17dBi~0.2dBi	
Peak Efficiency	41.3%	
Average Efficiency across the band	40.1%	
Efficiency Range across the band	37.8%~41.3%	



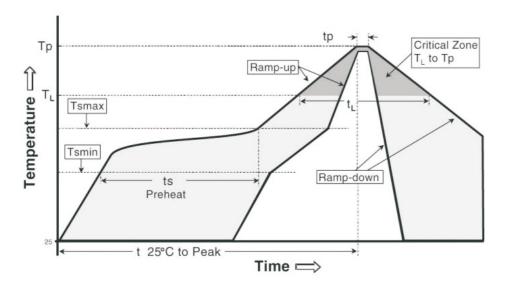


Part name	3.2 *1.6 *0.4 mm³ SMD Antenna	Date	2025-08-06
Part number	L-KLS1-WIFI-SMD3216	Edition	V1
Department		Page	7/9



SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage is as follows:

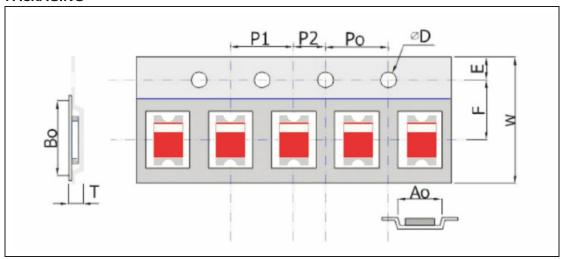


Phase	Profile features	Pb-Free assembly (SnAgCu)	
RAMP-UP	Avg. Ramp-up Rate (Tsmax to Tp)	3 °C / second (max.)	
PREHEAT	- Temperature Min (Tsmin) - Temperature Max (Tsmax) - Time (tsmin to tsmax)	150 °C 200 °C 60-180 seconds	
REFLOW	- Temperature (TL) - Total Time above TL (tL)	217 °C 60-150 seconds	
PEAK	- Temperature (Tp) - Time (tp)	260 °C 20-40 seconds	
RAMP-DOWN	Rate	6 °C/second max	
Time from 25 °C to Peak Temperature		8 minutes max	



Part name	3.2 *1.6 *0.4 mm ³ SMD Antenna	Date	2025-08-06
Part number	L-KLS1-WIFI-SMD3216	Edition	V1
Department		Page	8/9

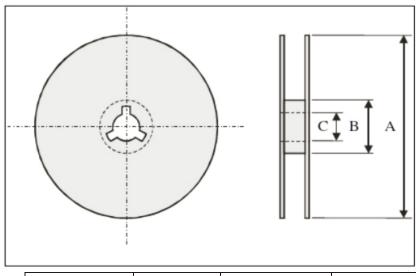
PACKAGING



Plastic Tape specification (unit:mm)

Index	Ao	Во	Фр	Т	W
Dimension (mm)	2.0±0.1	3.6±0.1	1.55±0.05	0.9±0.1	8.2±0.1
Index	E	F	Ро	P1	P2
Dimension (mm)	1.75±0.1	3.2±0.1	4.0±0.1	4.0±0.1	2.0±0.1

Reel dimensions



 Index
 A
 B
 C

 Dimension(mm)
 178
 60
 13.5

Typing Quantity: 3000 pieces per reel.

CAUTION OF HANDLING

Storage environment condition

Products shoud be storage in the warehouse on the following conditions:

Temperature : -10° C ~+40 $^{\circ}$ C



Part name	3.2 *1.6 *0.4 mm ³ SMD Antenna	Date	2025-08-06
Part number	L-KLS1-WIFI-SMD3216	Edition	V1
Department		Page	9/9

Humidity : 30% to 70% relative humidity

Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.

Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.

Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.

Products should be storage under the airtight packaged condition.